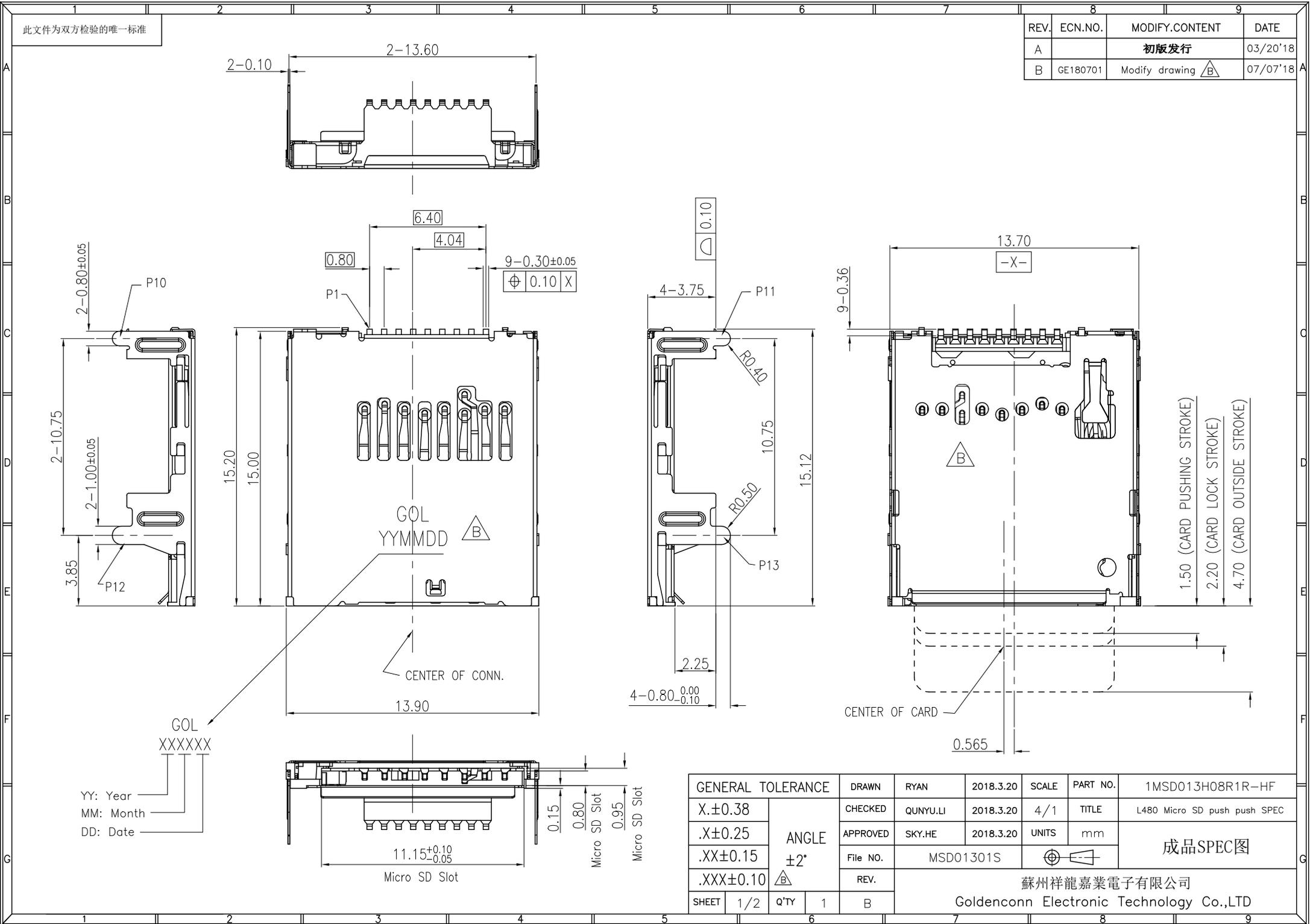


此文件为双方检验的唯一标准

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		初版发行	03/20'18
B	GE180701	Modify drawing $\triangle B$	07/07'18

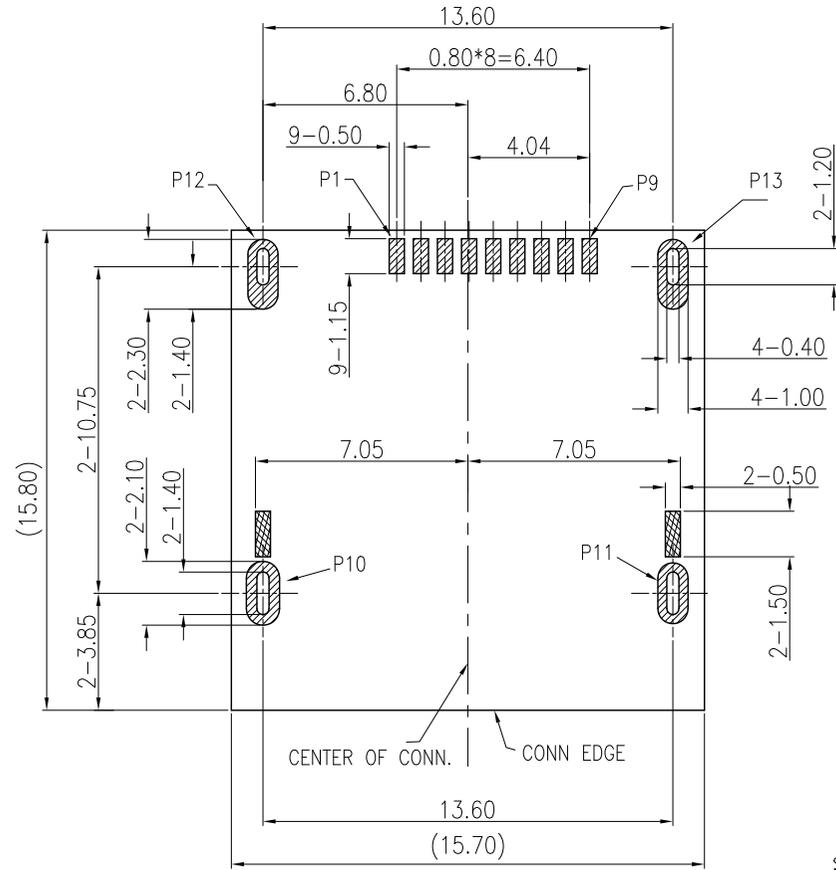


GOL  
XXXXXX

YY: Year  
MM: Month  
DD: Date

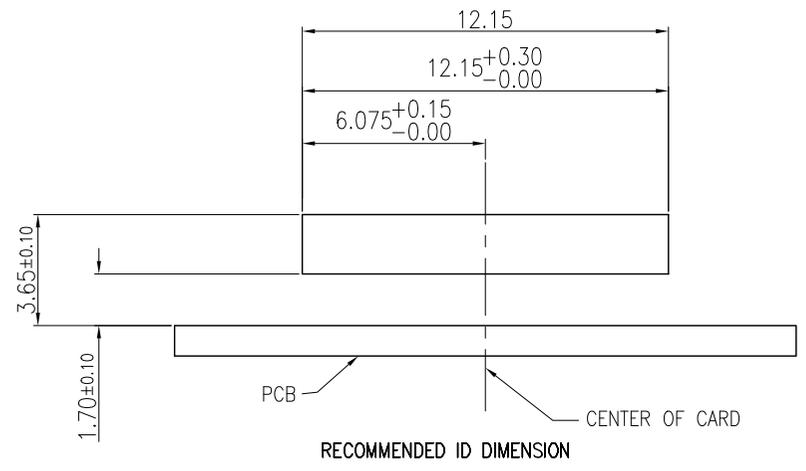
GENERAL TOLERANCE		DRAWN	RYAN	2018.3.20	SCALE	PART NO.	1MSD013H08R1R-HF
X.±0.38	ANGLE ±2° $\triangle B$	CHECKED	QUNYU.LI	2018.3.20	4/1	TITLE	L480 Micro SD push push SPEC
.X±0.25		APPROVED	SKY.HE	2018.3.20	UNITS	mm	成品SPEC图
.XX±0.15		File NO.	MSD01301S				
.XXX±0.10		REV.	蘇州祥龍嘉業電子有限公司				
SHEET 1/2	Q'TY 1	B	Goldenconn Electronic Technology Co.,LTD				

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		初版发行	03/20'18
B	GE180701	Modify drawing	07/07'18



- PAD AREA
  - VIA AND TRACE KEEPOUT AREA
  - OTHER COMPONENT KEEPOUT AREA
- RECOMMENDED PCB LAYOUT (TOLERANCE: ±0.05)

- 1.MATERIAL:
- 1.1 Insulator:High Temperature Thermoplastic, LCP,UL94V-0, Black
  - 1.2 Contact: Phosphor Bronze(C5210R-H,T=0.15±0.03mm)
  - 1.3 Shell: SUS304-H T=0.12±0.03mm
- 2.Plating:
- 2.1 Contact: Plated 50u''min Ni Overall  
Plated 3u''min Au Selective contact area  
Plated 80u''min Matte-tin over Ni on solder area
  - 2.2 Shell: Plated 50u''min Solderability Ni Overall
- 3.Property:
- 3.1 Current Rating :0.5A AC/DC max.
  - 3.2 Voltage Rating :3.3V/5V(AC/DC)
  - 3.3 Contact Resistance:Contact Pin 100mΩ max.
  - 3.4 Insert/Pulling Force: 40N Max / 0.5~40N
  - 3.5 Smt Solder Temperature: Should Under 260°C
  - 3.6 Operation Temperature Range: -40~+85°C
  - 3.7 Product Compliant to ROHS And Halogen Free.



PIN ASSIGNMENT

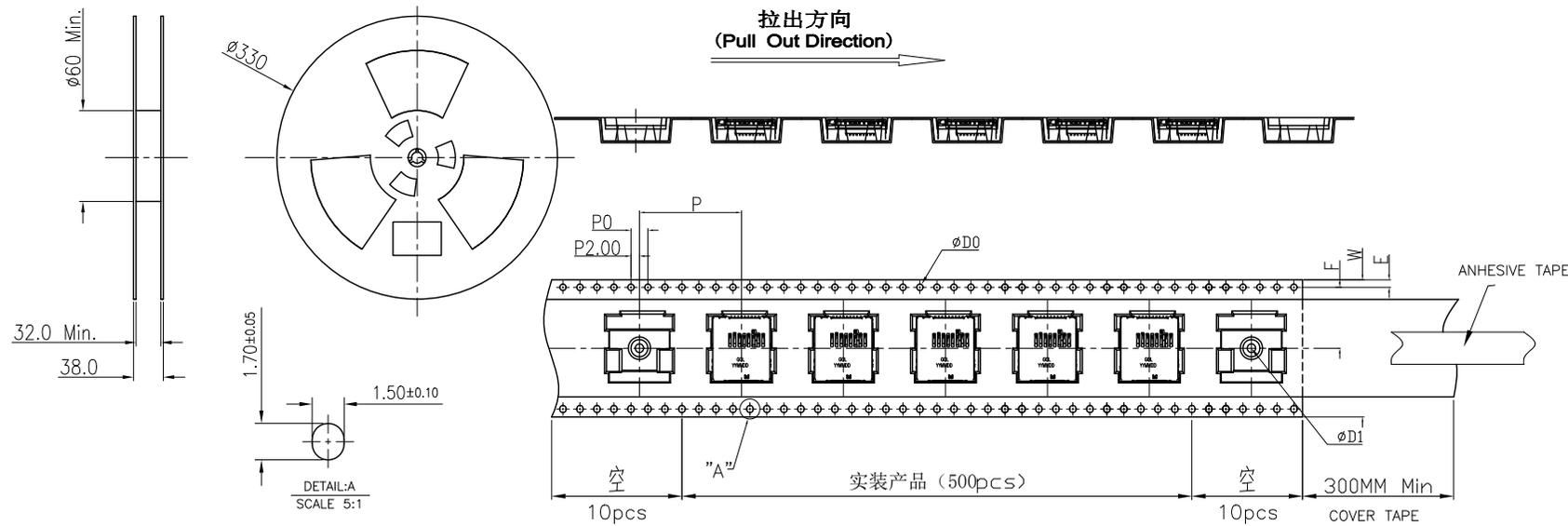
Pin No.	Pin Assignment
P1	MICRO SD DAT2
P2	MICRO SD CD/DAT3
P3	MICRO SD CMD
P4	MICRO SD VDD1
P5	MICRO SD CLK
P6	MICRO SD VSS
P7	MICRO SD DAT0/RCL
P8	MICRO SD DAT1/RCL
P9	MICRO SD CD
P10	GND
P11	GND
P12	GND
P13	GND

Opening/Close of Switch

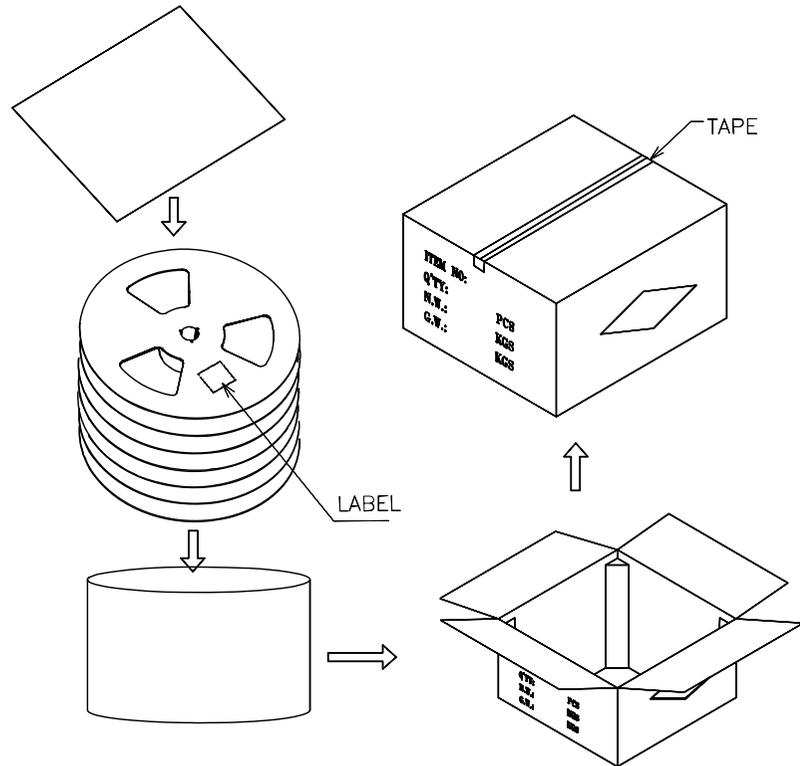
Card Detect Switch	
Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
N/O	

GENERAL TOLERANCE	DRAWN	RYAN	2018.3.20	SCALE	PART NO.	1MSD013H08R1R-HF
X.±0.38	CHECKED	QUNYU.LI	2018.3.20	4/1	TITLE	L480 Micro SD push push SPEC
.X±0.25	APPROVED	SKY.HE	2018.3.20	UNITS	mm	成品SPEC图
.XX±0.15	File NO.	MSD01301S				
.XXX±0.10	REV.	蘇州祥龍嘉業電子有限公司				
SHEET 2/2	Q'TY 1	B	Goldenconn Electronic Technology Co.,LTD			

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		初版发行	08/15'18



尺寸栏	
E	1.75±0.10
S	28.40±0.10
F	14.20±0.20
P2	2.00±0.10
∅Do	1.50 <sup>+0.10</sup> <sub>0</sub>
∅D1	2.00±0.10
Po	4.00±0.10
10Po	40.00±0.20
W	32.00±0.30
P	24.00±0.20
Ao	14.10±0.15
BO	15.33±0.15
KO	5.45±0.15
t	0.40±0.05



**备注:**

1. 把检验好的产品一一放入卷盘内, 方向需一致. 将装好产品的载带进行包装, 机. 每盘数量共500PCS /卷
2. 将装好产品之卷盘平放入纸箱内, 叠加方向须一致, 共7卷/箱. 用封箱胶纸封好纸箱 (共3500Pcs/箱), 并在外箱侧面右上角贴上外箱标签(如图所示)
3. 如出现尾数或有未装满之零数量, 须在卷盘及外箱上以标签明示.
4. 在搬运及运输中, 轻拿轻放, 不可有重压现象.
5. 盖带的剥离力要求: 20-130gf.

1	1MSD013H08R1R-HF	500	7	3500	/	350*350*300
ITEM	PRODUCT NO.	Q'TY/REEL	REEL/CARTON	Q'TY/CARTON	Kg/CARTON	CARTON SIZE

GENERAL TOLERANCE		DRAWN	RYAN	2018.3.20	SCALE	PART NO.	1MSD013H08R1R-HF
X.±0.30	ANGLE ±2°	CHECKED	QUNYU.LI	2018.3.20	/	TITLE	L480 Micro SD push push
.X±0.20		APPROVED	SKY.HE	2018.3.20	UNITS	mm	成品包装规范
.XX±0.10		File NO.	MSD01301P				
.XXX±0.05		REV.	蘇州祥龍嘉業電子有限公司				
SHEET 1/1	Q'TY 1	A	Goldenconn Electronic Technology Co.,LTD				